

HPAL1V0530

High current inductor



Product features

- High current carrying capacity
- Low core losses
- Magnetically shielded, low EMI
- Inductance range from 0.1 μH to 10 μH
- Current range from 3.0 A to 30 A
- 5.75 mm x 5.4 mm footprint surface mount package in a 3.0 mm height
- Iron powder core material
- Moisture Sensitivity Level (MSL) 1

Applications

- Voltage Regulator Module (VRM)
- Multi-phase regulators
- Point-of-load modules (PoL)
- Desktop and server VRMs and EVRDs
- Base station equipment
- Notebook and laptop regulators
- Battery power systems
- Graphics cards
- Data networking and storage systems

Environmental compliance and general specifications

- Storage temperature range (Component): -55 °C to +125 °C
- Operating temperature range: -55 °C to +125 °C (ambient plus self-temperature rise)



Product specifications

Part number ⁵	OCL ¹ (μH) \pm 20%	FLL ² (μH) minimum	I_{rms}^3 (A)	I_{sat}^4 (A)	DCR (m Ω) typical @ +20 °C	DCR (m Ω) maximum @ +20 °C
HPAL1V0530-R10-R	0.10	0.056	25	30	2.6	3.0
HPAL1V0530-R20-R	0.20	0.112	16	20	3.7	3.9
HPAL1V0530-R33-R	0.33	0.185	14	18	4.97	5.5
HPAL1V0530-R47-R	0.47	0.264	11	15	6.5	8.5
HPAL1V0530-R68-R	0.68	0.381	9.0	11.5	8.6	10
HPAL1V0530-1R0-R	1.0	0.56	8.5	10	11	14
HPAL1V0530-1R2-R	1.2	0.68	8.0	9.5	13.1	16
HPAL1V0530-1R5-R	1.5	0.84	7.5	9.0	16.5	20
HPAL1V0530-2R2-R	2.2	1.24	7.0	7.0	25	29
HPAL1V0530-3R3-R	3.3	1.85	5.5	6.0	33	38
HPAL1V0530-4R7-R	4.7	2.64	4.5	4.6	50	60
HPAL1V0530-6R8-R	6.8	3.81	3.5	3.6	80	90
HPAL1V0530-100-R	10.0	5.60	3.0	3.5	110	125

1. Open circuit inductance (OCL) test parameters: 100 kHz, 1.0 V_{rms}, 0.0 Adc, +25 °C

2. Full load inductance (FLL) test parameters: 100 kHz, 1.0 V_{rms}, I_{sat}, +25 °C

3. I_{DC}: DC current for an approximate temperature rise of 40 °C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed +125 °C under worst case operating conditions verified in the end application.

4. I_{sat}: Peak current for approximately 30% rolloff @ +25 °C

5. Part number definition: HPAL1V0530-xxx-R

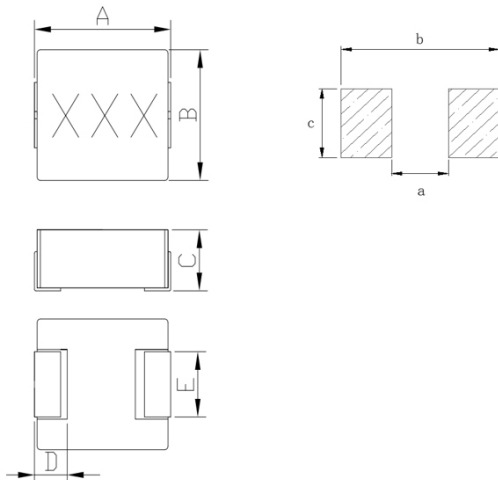
HPAL1V0530 = Product code and size

xxx= inductance value in μH , R= decimal point, If no R is present then last character equals number of zeros

-R suffix = RoHS compliant

Dimensions (mm)

Recommended pad layout



Part number	A	B	C	D	E	a	b	c
HPAL1V0530-xxx-R	5.4 \pm 0.35	5.2 \pm 0.20	2.8 \pm 0.20	1.2 \pm 0.2	2.2 \pm 0.3	2.2 typ	6.0 typ	2.5 typ

Part marking: xxx=inductance value in μH , R=decimal point. If no R is present then last character equals number of zeros.

All soldering surfaces to be coplanar within 0.1 millimeters

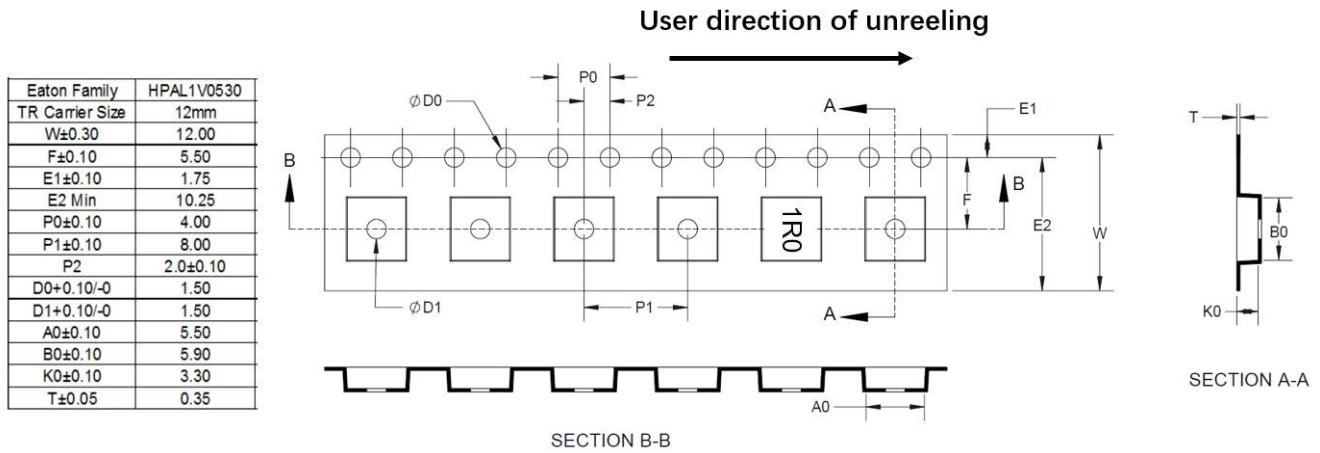
Tolerances are \pm 0.3 millimeters unless stated otherwise

Pad layout tolerance is \pm 0.1 millimeters unless stated otherwise

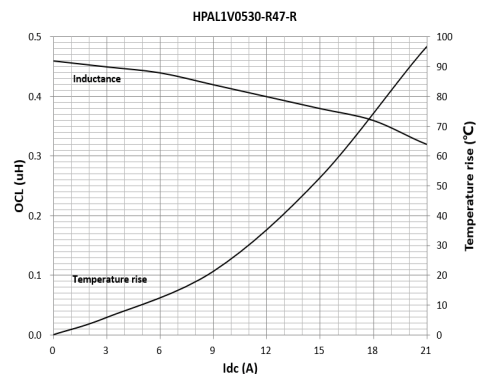
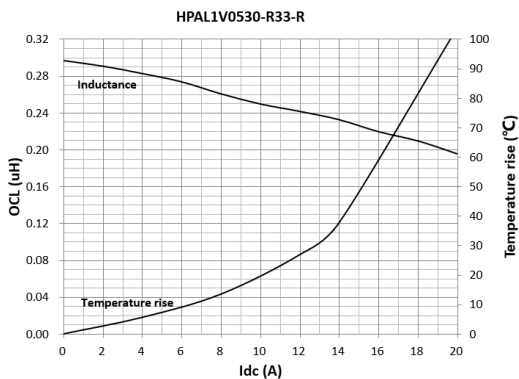
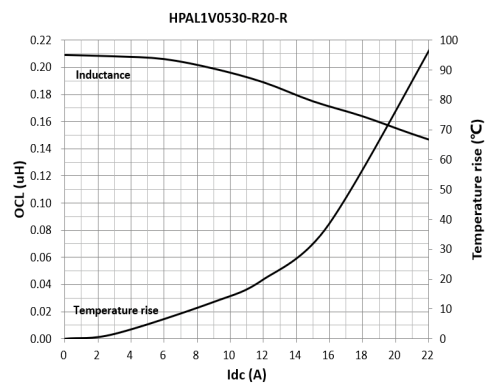
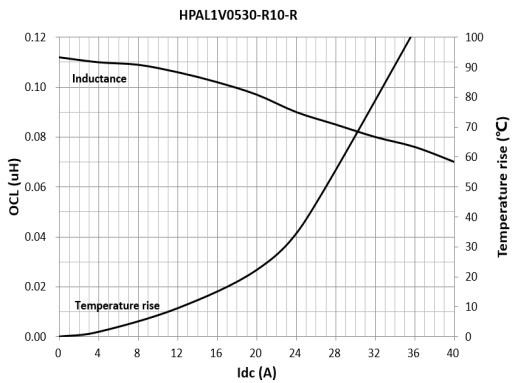
Traces or vias underneath the inductor is not recommended

Packaging information (mm)

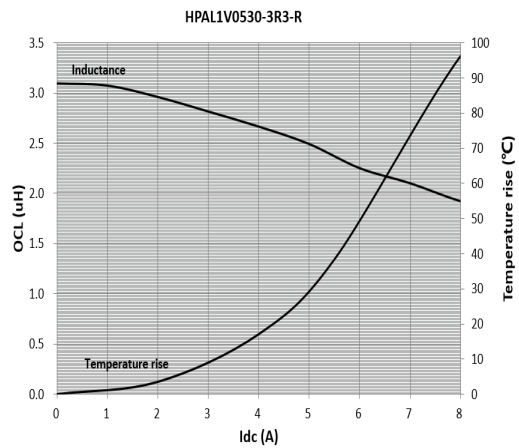
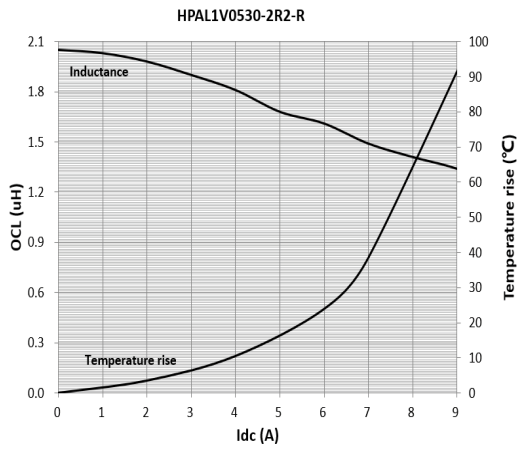
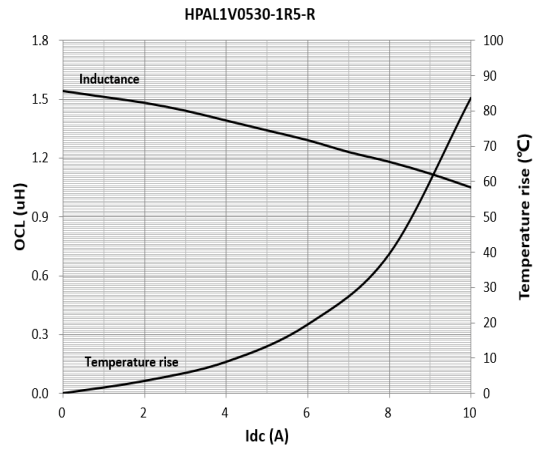
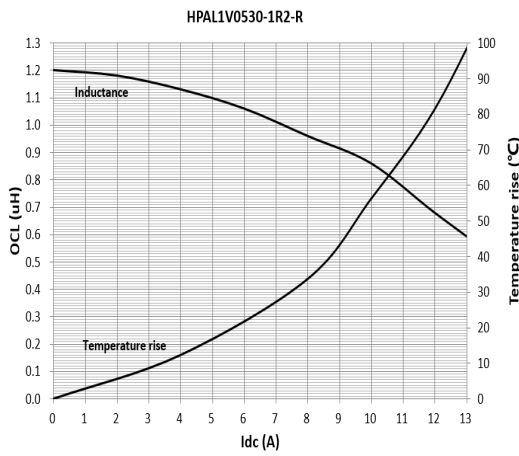
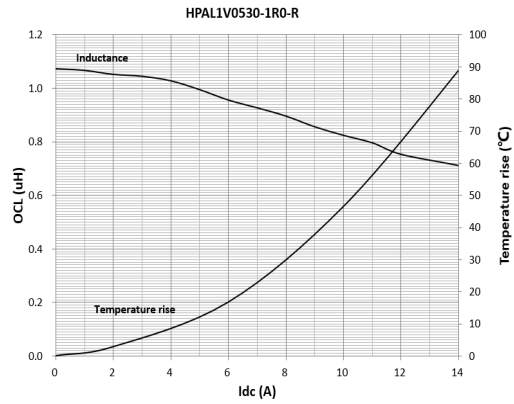
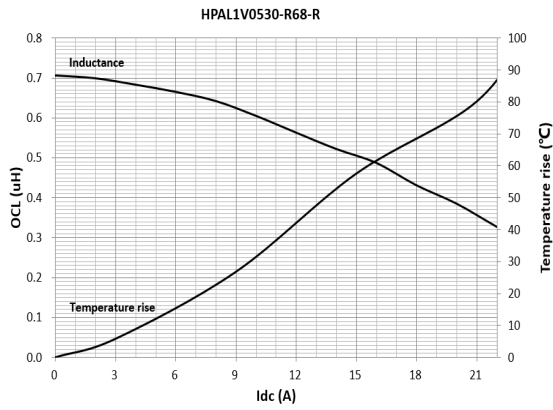
Supplied in tape and reel packaging, 2000 parts per 13" diameter reel



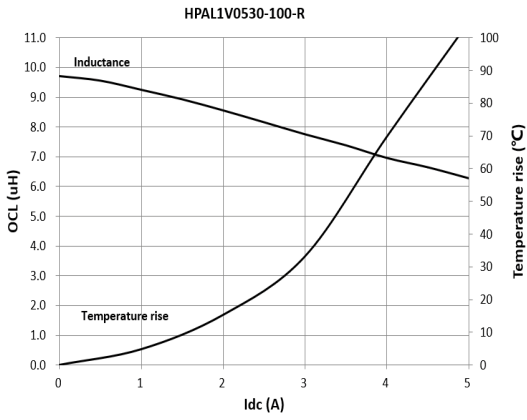
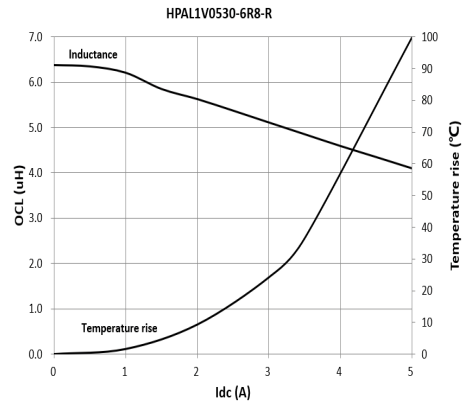
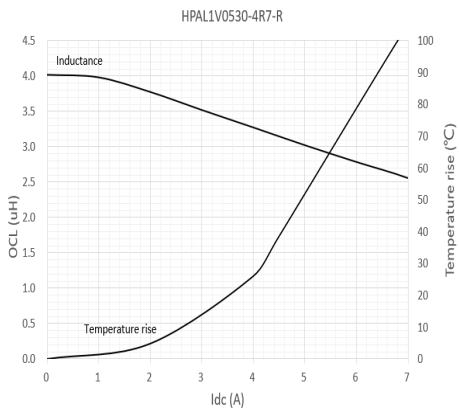
Inductance and temperature rise vs. current



Inductance and temperature rise vs. current



Inductance and temperature rise vs. current



Solder reflow profile

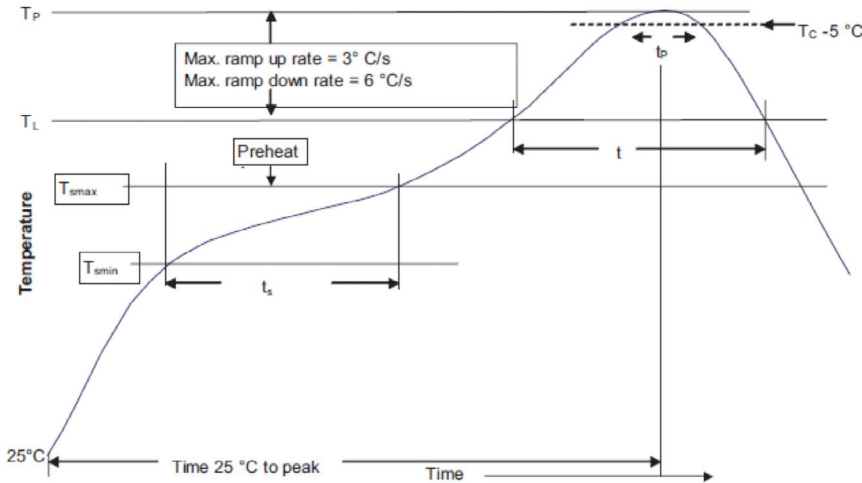


Table 1 - Standard SnPb solder (T_C)

Package thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5 mm)	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2 - Lead (Pb) free solder (T_C)

Package thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 – 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

Reference J-STD-020

Profile feature	Standard SnPb solder	Lead (Pb) free solder
Preheat and soak		
• Temperature min. (T_{smin})	100 °C	150 °C
• Temperature max. (T_{smax})	150 °C	200 °C
• Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds	60-120 seconds
Ramp up rate T_L to T_P	3 °C/ second max.	3 °C/ second max.
Liquidous temperature (T_L)	183 °C	217 °C
Time (t_L) maintained above T_L	60-150 seconds	60-150 seconds
Peak package body temperature (T_P)*	Table 1	Table 2
Time (t_p)* within 5 °C of the specified classification temperature (T_C)	20 seconds*	30 seconds*
Ramp-down rate (T_P to T_L)	6 °C/ second max.	6 °C/ second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

* Tolerance for peak profile temperature (T_P) is defined as a supplier minimum and a user maximum.

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Eaton
Electronics Division
1000 Eaton Boulevard
Cleveland, OH 44122
United States
Eaton.com/electronics

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